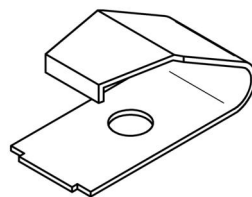
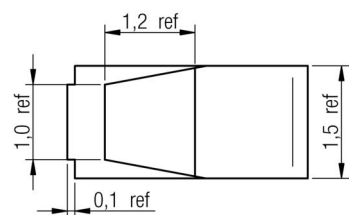
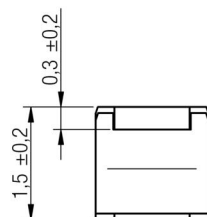
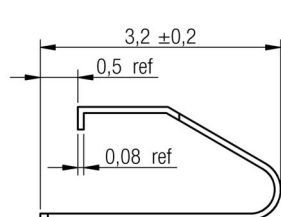
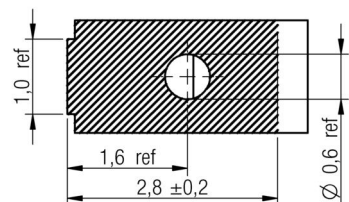
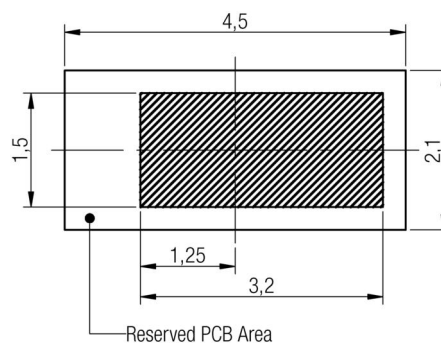
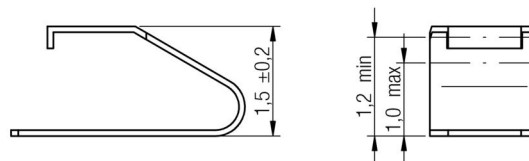


A Dimensions: [mm]

Scale - 10:1

B Recommended land pattern: [mm]

Scale - 10:1

C Recommended compression:

Scale - 10:1

**D Properties:**

Properties	Value
Material	Copper Beryllium (CuBe) gold-plated(AU)

E General information:

- Storage Temperature: -40°C to 90°C
- Operating Temperature: -40°C to 90°C

				Projection 		DESCRIPTION
1.5	2014-06-11	SSt	SSt			WE-SECF SMD EMI Contact Finger
1.4	2013-12-19	SSt	SSt			
1.3	2013-07-18	SSt	WJ			
1.2	2013-05-14	SSt	WJ			
1.1	2013-04-24	SSt	SSt			
1.0	2012-10-30	SSt	WJ			
REV	DATE	BY	CHECKED			

Würth Elektronik eiSos GmbH & Co. KG
EMC & Inductive Solutions
Max-Eyth-Str. 1
74638 Waldenburg
Germany
Tel. +49 (0) 79 42 945 - 0
www.we-online.com
eiSos@we-online.com

Order.- No.

331031321515

Size: 0315

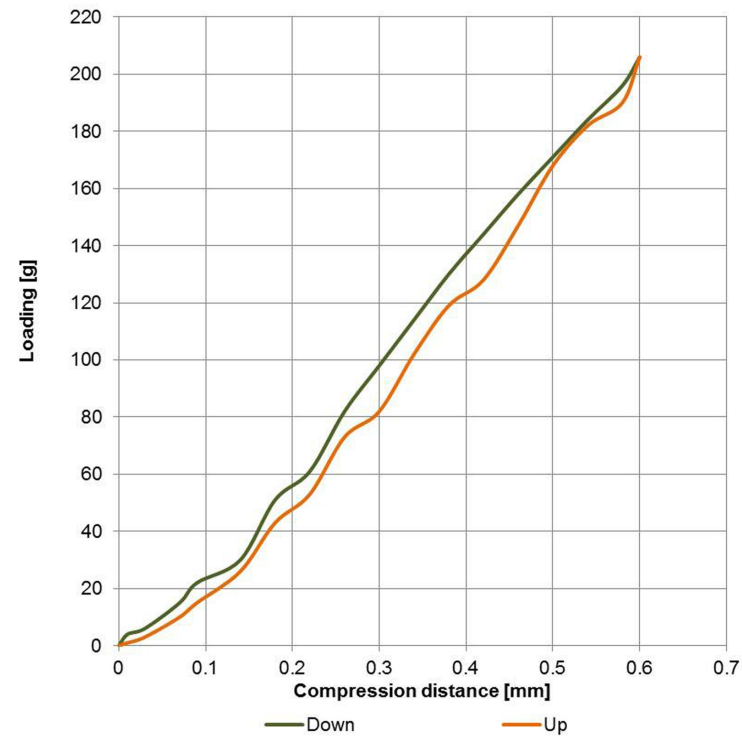


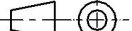

SIZE

A4



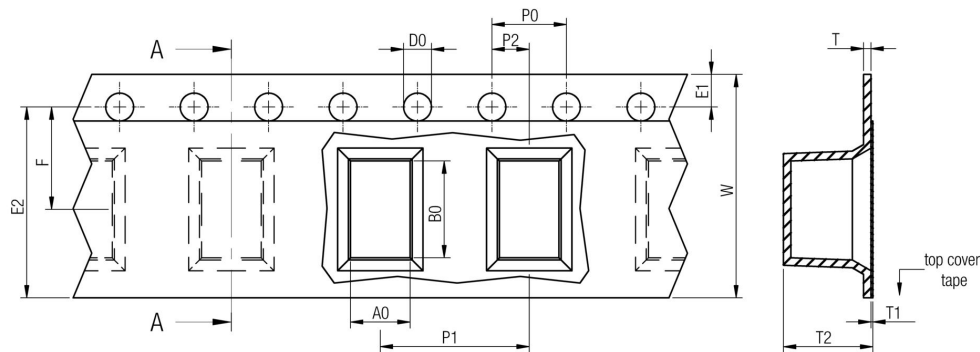
F Force Deflection Diagram:



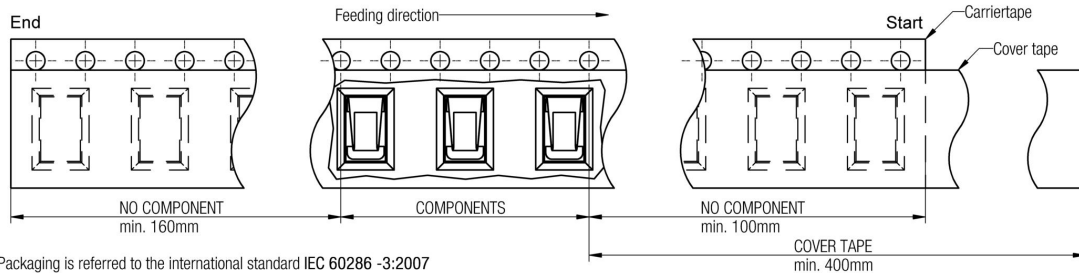
				<div>Projection</div> 		DESCRIPTION		
1.5	2014-06-11	SSt	SSt	<div>Würth Elektronik eiSos GmbH & Co. KG</div> <div>EMC & Inductive Solutions</div> <div>Max-Eyth-Str. 1</div> <div>74638 Waldenburg</div> <div>Germany</div> <div>Tel. +49 (0) 79 42 945 - 0</div> <div>www.we-online.com</div> <div>eiSos@we-online.com</div>		WE-SECF SMD EMI Contact Finger		
1.4	2013-12-19	SSt	SSt					
1.3	2013-07-18	SSt	WJ			Order.- No.	 <div>COMPLIANT</div> <div>RoHS&REACH</div> <div>WÜRTH ELEKTRONIK</div>	SIZE
1.2	2013-05-14	SSt	WJ					
1.1	2013-04-24	SSt	SSt					
1.0	2012-10-30	SSt	WJ					
REV	DATE	BY	CHECKED	Size: 0315				

This electronic component has been designed and developed for usage in general electronic equipment only. This product is not authorized for use in equipment where a higher safety standard and reliability standard is especially required or where a failure of the product is reasonably expected to cause severe personal injury or death, unless the parties have executed an agreement specifically governing such use. Moreover Würth Elektronik eiSos GmbH & Co KG products are neither designed nor intended for use in areas such as military, aerospace, aviation, nuclear control, submarine, transportation (automotive control, train control, ship control), transportation signal, disaster prevention, medical, public information network etc.. Würth Elektronik eiSos GmbH & Co KG must be informed about the intent of such usage before the design-in stage. In addition, sufficient reliability evaluation checks for safety must be performed on every electronic component which is used in electrical circuits that require high safety and reliability functions or performance.

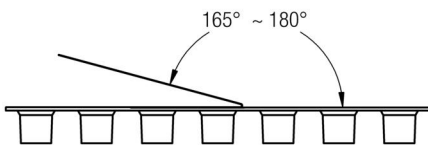
G Packaging Specification - Tape and Reel [mm]:



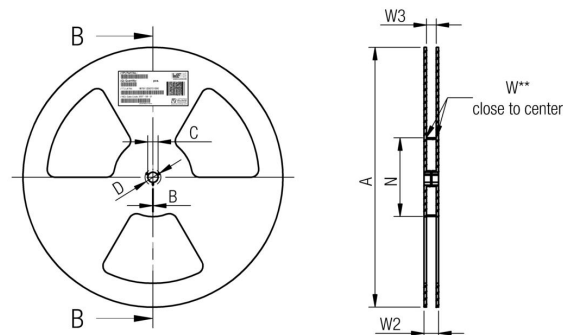
	A0	B0	W	P1	T	T1	T2	D0	E1	E2	F	P0	P2	Tape	VPE / packaging unit
tolerance	typ.	typ.	± 0.3	± 0.1	± 0.1	max.	typ.	+0.1 -0.0	± 0.1	min.	± 0.05	± 0.1	± 0.05		
size	0135	2.20	4.90	12.00	8.00	0.40	0.10	6.30	1.50	1.75	10.25	5.50	4.00	2.00	Polystyrene 2000
	0148	2.20	4.70	16.00	8.00	0.40	0.10	7.20	1.50	1.75	14.25	7.50	4.00	2.00	Polystyrene 1500
	0320	1.60	2.85	12.00	8.00	0.30	0.10	2.50	1.50	1.75	10.25	5.50	4.00	2.00	Polystyrene 3500
	0315	1.70	3.30	12.00	8.00	0.30	0.10	2.10	1.50	1.75	10.25	5.50	4.00	2.00	Polystyrene 4500
	0453	2.25	4.25	12.00	8.00	0.40	0.10	6.00	1.50	1.75	10.25	5.50	4.00	2.00	Polystyrene 1500
	0557	2.20	4.90	12.00	8.00	0.40	0.10	6.30	1.50	1.75	10.25	5.50	4.00	2.00	Polystyrene 1500
	0610	3.20	6.20	16.00	12.00	0.50	0.10	10.70	1.50	1.75	14.25	7.50	4.00	2.00	Polystyrene 500
	0825	2.10	3.20	12.00	4.00	0.40	0.10	3.20	1.50	1.75	10.25	5.50	4.00	2.00	Polystyrene 5500
	1440	2.75	3.75	12.00	8.00	0.35	0.10	4.65	1.50	1.75	10.25	5.50	4.00	2.00	Polystyrene 2000
	1562	2.70	7.15	16.00	8.00	0.35	0.10	6.80	1.50	1.75	14.25	7.50	4.00	2.00	Polystyrene 1200
	1670	2.20	4.70	16.00	8.00	0.40	0.10	7.60	1.50	1.75	14.25	7.50	4.00	2.00	Polystyrene 1000
	1613	2.75	7.25	24.00	16.00	0.50	0.10	13.90	1.50	1.75	22.25	11.50	4.00	2.00	Polystyrene 200
	1730	2.30	3.30	12.00	8.00	0.35	0.10	3.75	1.50	1.75	10.25	5.50	4.00	2.00	Polystyrene 2500
	1735	2.20	3.20	12.00	8.00	0.35	0.10	4.60	1.50	1.75	10.25	5.50	4.00	2.00	Polystyrene 2000
	2140	3.20	5.20	12.00	8.00	0.40	0.10	4.80	1.50	1.75	10.25	5.50	4.00	2.00	Polystyrene 2000
	2240	2.10	6.10	16.00	8.00	0.40	0.10	4.60	1.50	1.75	14.25	7.50	4.00	2.00	Polystyrene 1800



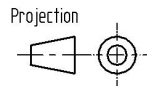
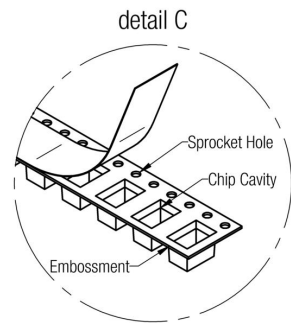
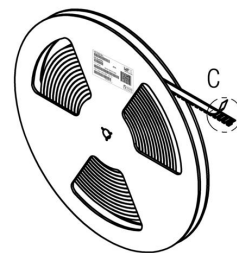
Packaging is referred to the international standard IEC 60286 -3:2007



		Pull-of force
Tape width	12 mm	0,1 N - 1,3 N
	16 mm	0,1 N - 1,3 N
	24 mm	0,1 N - 1,3 N



	A	B	C	D	N	W1	W2	W3	W3
tolerance	± 2.0	min.	± 0.8	min.	min.	+ 1.5	max.	min.	max.
Tape width	12 mm	330,00	1,50	13,00	20,20	100,00	12,40	18,40	11,90 15,40
	16 mm	330,00	1,50	13,00	20,20	100,00	16,40	22,40	15,90 19,40
	24 mm	330,00	1,50	13,00	20,20	100,00	24,40	30,40	23,90 27,40



DESCRIPTION

WE-SECF SMD EMI Contact Finger

Order.- No.

331031321515

Size: 0315



SIZE

A4

H Soldering Specifications:



H1: Classification Reflow Profile for SMT components:



H2: Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Preheat <ul style="list-style-type: none">- Temperature Min (T_{smin})- Temperature Max (T_{smax})- Time (t_s) from (T_{smin} to T_{smax})	150°C 200°C 60-120 seconds
Ramp-up rate (T_L to T_p)	3°C/ second max.
Liquidous temperature (T_L) Time (t_L) maintained above T_L	217°C 60-150 seconds
Peak package body temperature (T_p)	See Table H3
Time within 5°C of actual peak temperature (t_p)	20-30 seconds
Ramp-down rate (T_p to T_L)	6°C/ second max.
Time 25°C to peak temperature	8 minutes max.

refer to IPC/JEDEC J-STD-020D

H3: Package Classification Reflow Temperature

	Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
PB-Free Assembly	< 1.6 mm	260°C	260°C	260°C
PB-Free Assembly	1.6 - 2.5 mm	260°C	250°C	245°C
PB-Free Assembly	≥ 2.5 mm	250°C	245°C	245°C

refer to IPC/JEDEC J-STD-020D

This electronic component has been designed and developed for usage in general electronic equipment only. This product is not authorized for use in equipment where a higher safety standard and reliability standard is especially required or where a failure of the product is reasonably expected to cause severe personal injury or death, unless the parties have executed an agreement specifically governing such use. Moreover Würth Elektronik eiSos GmbH & Co KG products are neither designed nor intended for use in areas such as military, aerospace, aviation, nuclear control, submarine, transportation (automotive control, train control), transportation signal, disaster prevention, medical, public information network etc.. Würth Elektronik eiSos GmbH & Co KG must be informed about the intent of such usage before the design-in stage. In addition, sufficient reliability evaluation checks for safety must be performed on every electronic component which is used in electrical circuits that require high safety and reliability functions or performance.

				Projection 		DESCRIPTION
1.5	2014-06-11	SSt	SSt			WE-SECF SMD EMI Contact Finger
1.4	2013-12-19	SSt	SSt			
1.3	2013-07-18	SSt	WJ			
1.2	2013-05-14	SSt	WJ			
1.1	2013-04-24	SSt	SSt			
1.0	2012-10-30	SSt	WJ			
REV	DATE	BY	CHECKED			

Würth Elektronik eiSos GmbH & Co. KG
EMC & Inductive Solutions
Max-Eyth-Str. 1
74638 Waldenburg
Germany
Tel. +49 (0) 79 42 945 - 0
www.we-online.com
eiSos@we-online.com

Order.- No.

331031321515

Size: 0315

COMPLIANT
RoHS&REACH
WÜRTH ELEKTRONIK

SIZE
A4

I Cautions and Warnings:

The following conditions apply to all goods within the product series of WE-SECF of Würth Elektronik eiSos GmbH & Co. KG:

General:

All recommendations according to the general technical specifications of the data sheet have to be complied with.

The responsibility for the applicability of customer specific products and use in a particular customer design is always within the authority of the customer. All technical specifications for standard products do also apply to customer specific products.

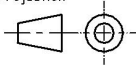

Product specific:

Follow all instructions mentioned in the data sheet, especially:

- The soldering profile has to be complied with according to the technical reflow soldering specification, otherwise this will void the warranty.
- To avoid contact finger misplacement and the coming off the soldering joints use maximum adjusted force at the Pick- and Place machine that does not exceed the recommended compression rate (of the contact fingers).
- The soldering joints must be kept clean, dry and grease free. The contact finger should be placed onto the solder pad of the printed circuit board in a way that no tin- solder is able to come into the undermost or the first elastic bending of the contact fingers so that the bending will not be affected.
- The contact finger shall not exceed the recommended compression rate. If recommended compression rate is exceeded there is a risk that the spring will not be able to push back into the initial state.
- Do not bend the contact finger into the opposite position, as the material will overstretch and possibly break.
- Violation of the technical product specifications will void the warranty.

The general and product specific cautions comply with the state of the scientific and technical knowledge and are believed to be accurate and reliable; however, no responsibility is assumed for inaccuracies or incompleteness.



				<div>Projection</div> 		DESCRIPTION
1.5	2014-06-11	SSt	SSt	<div>Würth Elektronik eiSos GmbH & Co. KG</div> <div>EMC & Inductive Solutions</div> <div>Max-Eyth-Str. 1</div> <div>74638 Waldenburg</div> <div>Germany</div> <div>Tel. +49 (0) 79 42 945 - 0</div> <div>www.we-online.com</div> <div>eiSos@we-online.com</div>	<div><div>WE-SECF SMD EMI Contact Finger</div></div>	
1.4	2013-12-19	SSt	SSt			
1.3	2013-07-18	SSt	WJ			
1.2	2013-05-14	SSt	WJ			
1.1	2013-04-24	SSt	SSt			
1.0	2012-10-30	SSt	WJ			
REV	DATE	BY	CHECKED	<div>Order. - No.</div> <div><div><div><div>COMPLIANT</div><div>RoHS&REACH</div><div>WÜRTH ELEKTRONIK</div></div></div></div> <div>Size: 0315</div>		<div>SIZE</div> <div>A4</div>

